

Start Up Pitches

Coming Soon

J. Kinaret
Executive Director
Chips JU, Brussels, Belgium



Abstract

Coming Soon

Biography

Jari Kinaret was born in Finland and holds M.Sc. degrees in Theoretical Physics and Electrical Engineering from the University of Oulu in 1986 and 1987, respectively, and a Ph.D. in Physics from the Massachusetts Institute of Technology (MIT) in 1992. Prof. Kinaret has worked in various roles at research institutes and universities in Copenhagen, Denmark, and Gothenburg, Sweden. From 2013 to 2023, he served as the Director of the Graphene Flagship, a one-billion-euro research project dedicated to exploring the potential of graphene. In October 2023, Prof. Jari Kinaret assumed the role of Executive Director at Chips Joint Undertaking (Chips JU), a European public-private partnership that supports research, development, innovation, and future manufacturing capacities in the European semiconductor ecosystem.

References

Beyond Glass: Flexiramics for Next-Generation RF and Thermal Substrates

A. Wynn
CEO
Flexiramics B.V, Enschede, The Netherlands



Abstract

Recent evaluations and early application trials have demonstrated that Flexiramics®, a European-developed ceramic microfiber nonwoven reinforcement, can deliver measurable benefits in XY thermal spreading and RF/mmWave stability when integrated into advanced substrate and packaging materials. These results represent a new development in reinforcement architectures for high-frequency and high-thermal-load electronics, offering an alternative to traditional woven glass fabrics.

As devices move into the 28–110 GHz domain and thermal densities continue to rise, the limitations of glass-reinforced dielectrics are becoming more pronounced. Woven glass introduces anisotropy, resin-rich pockets, and local dielectric variation, all of which can affect signal uniformity and thermal performance. These constraints are increasingly visible in multilayer substrates, advanced packaging, and next-generation RF systems.

Flexiramics addresses these challenges through a continuous ceramic micro-network that can be incorporated into existing polymer matrices and lamination processes.

Recent test data and early customer evaluations indicate three key areas of impact:

- XY thermal dissipation - application trials show that the ceramic network supports more efficient lateral heat spreading, helping reduce hotspot formation. This is designed to support improved thermal stability in high-density architectures
- RF/mmWave stability - initial RF measurements demonstrate stable dielectric behaviour across 30–110 GHz, with reduced sensitivity to local reinforcement effects. This is particularly relevant for communication, radar, sensing, and advanced packaging applications
- Beyond glass - by eliminating woven-fabric artifacts, Flexiramics provides a more uniform reinforcement environment. Early evaluations indicate more predictable electrical behaviour across the panel compared to glass-based systems

Beyond technical performance, Flexiramics contributes to broader European strategic objectives. The platform is developed and manufactured within the EU, supporting regional supply-chain resilience for advanced materials. Its scalable production approach enables both early-stage prototyping and industrial-scale deployment.

The presentation will share new evaluation data, application examples, and insights from ongoing collaborations, illustrating how a new reinforcement architecture can help Europe advance toward more capable, efficient, and reliable electronic systems.

Biography

Andy is a technology leader with 30 years' experience transforming new technologies into successful global businesses. Former CTO of Morgan Advanced Materials plc, \$1.5 Billion FTSE 250 multinational. Brings deep expertise in aligning innovation and business strategy across industries and geographies, including 6+ years based in China.

Led commercialization of \$2B of new tech sales in renewable energy, EVs, medical devices, semicon & more. Held senior exec roles (CTO, CEO, Board Director, Programme Director) with responsibility for global P&L, innovation, strategy, and major restructuring programmes.

Built and scaled businesses internationally: launched ventures across Asia, built factories in China/ME/Asia, turned around US operations, and re-engineered production lines worldwide.

Entrepreneurship: Co-Founder of TTIP Talent, TTIP Strategy, PurEmissions, and BLOK Capital. Educator & thought leader: keynote speaker, MBA faculty at IE & Warwick Business Schools, and author of *Transforming Technology into Profit*, *Cracking the Innovation Code*, and *Building an Innovation Powerhouse*.

The myth of troubleshooting

L. Messinger
CEO
Korra.ai, Jerusalem, Israel



Abstract

The pitch is familiar by now: troubleshooting is what keeps tools down, and AI will finally shorten MTTR. It is a compelling story. It is also two claims stacked on top of each other, and neither has been examined closely.

The first is empirical. How much of a technician's working day is actually spent troubleshooting? Measured against the full picture of setup, qualification, PM, documentation, handoffs and procedure execution, the answer is a much smaller fraction than the industry's attention would suggest.

The second is a matter of judgment. Even where troubleshooting does happen, it is the worst possible place to point a probabilistic system. It is the moment with the least tolerance for a confident wrong answer, the least structured input, and the highest cost of being subtly plausible instead of correct.

This talk argues that AI has been aimed at the most visible problem in the fab rather than the most valuable one, and presents an alternative: grounding AI in what the organization already knows, and separating diagnosis from procedures. We will enhance and present methods needed for real world use cases.

Biography

Lior Messinger is the founder and CEO of Korra.ai, an AI company building knowledge retrieval systems for industrial environments where the data cannot leave the building. Korra's platform runs fully on-premises and air-gapped, and is deployed in production across semiconductor manufacturing and field service operations. Lior has spent 35 years building software in high-consequence environments. He previously led physics and AI development for flight simulators and video games. He founded Korra in 2020 to let AI understand technical procedures using documentation text, visuals, and historical data.

References

Magnetocalorics: Next-Generation Cooling for Semiconductors

R. Dubois

COO

Magnoric, Duppigheim, France

Abstract

Magnoric is developing a new generation of cooling systems based on the magnetocaloric effect, replacing conventional vapor-compression technology with a solid-state thermodynamic cycle.

Our technology operates without refrigerant gases and combines high energy-efficiency potential with silent, vibration-free operation and reduced maintenance requirements.

Magnoric has already developed and validated pre-series cooling platforms from a few hundred watts to more than 1 kW and is now scaling the technology toward higher-power applications.

For the semiconductor industry, magnetocaloric cooling opens new opportunities for efficient thermal management, process cooling and heat recovery. This presentation will introduce Magnoric's technology, its latest developments and its potential for next-generation semiconductor manufacturing applications.

Biography

Rémi Dubois is Chief Operating Officer at Magnoric, a French deep-tech company developing magnetocaloric cooling technologies. He is responsible for operations, business development and the industrialization of Magnoric's technology, working closely with industrial partners across cooling, energy and advanced manufacturing applications.

References